

Value Communications Appliance Reference Schematics

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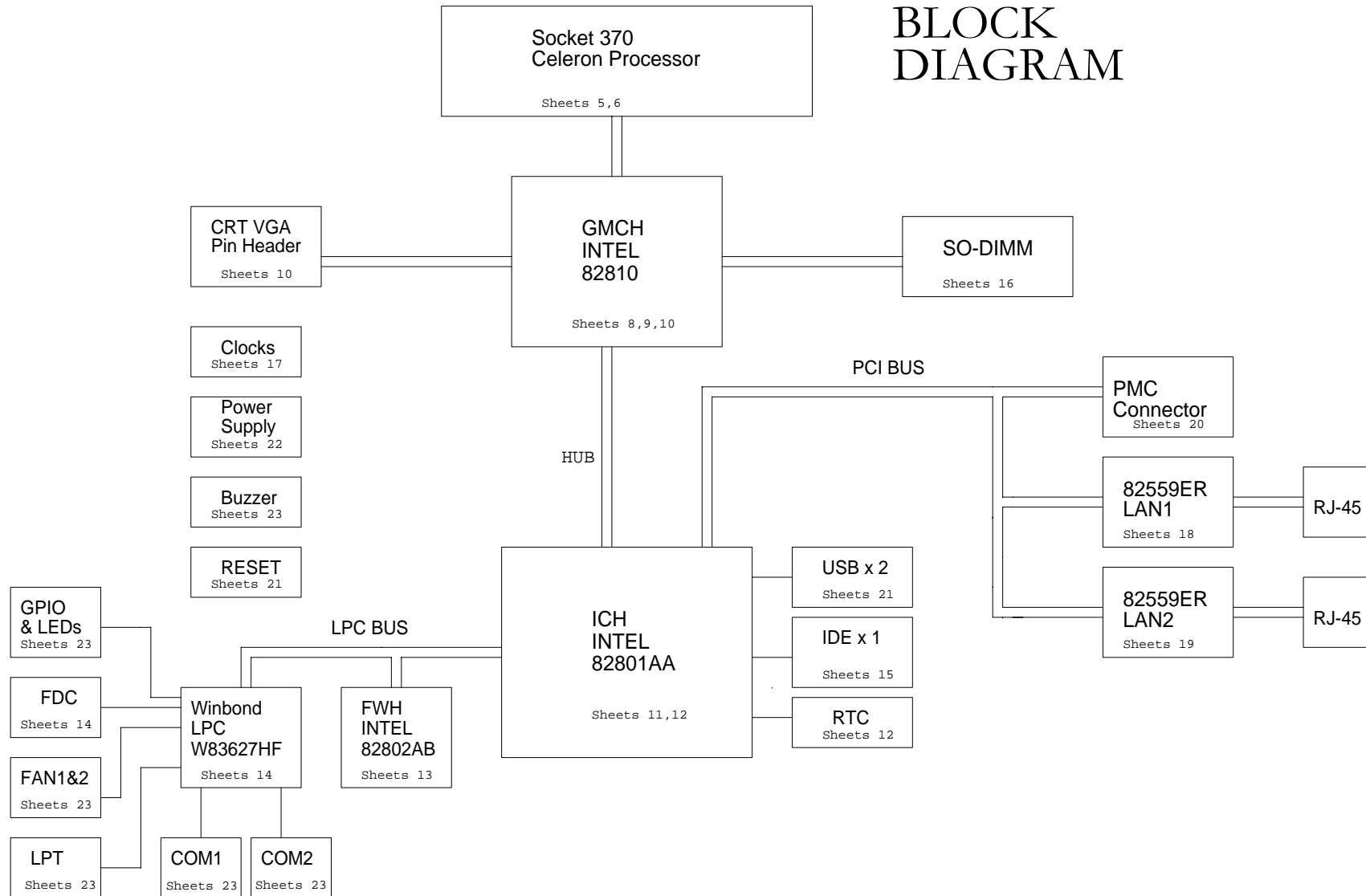
Revision History

03/14/2000 Revision A0 -- Initial release.

These schematics are preliminary and subject to change without notice.

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BLOCK DIAGRAM



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Block Diagram

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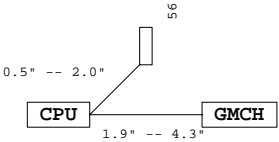
General Board Design Requirements

- >> PCB must be routed using six (6) layers, with the following stackup:
 - Layer 1: Signal, V1P5,V1P8, V2P5, and V5P0 Busses
 - Layer 2: GND
 - Layer 3: Signal
 - Layer 4: Signal
 - Layer 5: Split Power Plane -- V3P3 Plane, V2P0 Island
 - Layer 6: Signal

- >> Right angle traces must not be used.
- >> Vias for decoupling capacitors must be kept as close as possible to the capacitor pad.
- >> Trace impedance must be 65 ohms, +/- 10%
- >> Total board thickness must be .062".
- >> Board material must be FR-4.
- >> GND layers must not be split.
- >> Top and bottom (outer) layers must be no less than 1/2 oz copper before plating, inner layers must be 1 oz copper.
- >> Series terminating resistors must be kept as close to the driving pin as possible.
- >> Daisy chain signals going to more that on point, do not use stubs.
- >> Unless otherwise noted, all signal traces must be between 5 and 6 mil width.
- >> Unless otherwise noted, minimum space between traces is 15 mils, including adjacent layers.
- >> Specific routing requirements are included throughout schematic sheets.
- >> One registration target must be included on each corner of the board.

CPU Routing Requirements

- >> Route all GTL traces between CPU and GMCH as shown in the diagram to the right.
- >> Route all traces between CPU and GMCH on a layer adjacent to a ground plane (preferably bottom layer), without layer changes.
- >> All traces between CPU and GMCH should differ in length by no more than 1000 mils.
- >> Minimum space between traces is 15 mils (unless otherwise noted), this includes adjacent signal layers.
- >> Minimum space between traces may be reduced to 5 mils when breaking out of a footprint. The total length of trace routed using 5 mil spacing must be less than 250 mils.
- >> The following signals require 25 mil spacing from other traces, including adjacent layers.
 - HA#[31:3], HD#[63:0], BREQ#0, ADS#, BNR#, BPRI#, HLOCK#, DEFER#, HTRDY#, DBSY#, DRDY#, HIT#, HITM#, A20M#, FLASH#, IGNNE#, INIT#, INTR, NMI, PWR_OK_2P5, SMI#, CPUSLP#, STPCLK#, 100/66#, FERR#, HRESET#, HREQ#[4:0], RS#[2:0], THERMD[P:N], CPU_GTL_REF[7:0], PLL[2:1], (TCK,TMS,TDI, TDO, TRST#, PRDY#, PREQ#).
- >> Route THRMDP and THRMND close together as a pair (no more than 250 mil difference in length), on same layer, in parallel, and 25 mils min from any other trace.
- >> Route CPU_GTLREF using 25 mil minimum width trace, and separate from all other traces by 25 mils minimum.
- >> Route PLL[2:1] using 25 mil minimum width trace, minimize loop area, and separate from all other traces by 25 mils minimum.



Clock Specific Routing Requirements

- >> A clock trace must not alternate layers.
- >> A clock trace must be separated by a minimum of 25 mils from any other trace, including serpentes, 11 mils is OK when going between pins or balls.
- >> The CPU clock length must be between 1" and 9", and 460 mils shorter than the GMCH clock. The GMCH_3V66 clock and ICH_3V66 clock must be matched in length. All PCI clocks must be matched in length, except for the PMC clock which must be 2" shorter than all other PCI clocks.
- >> SDRAM_CLK[1:0] must be matched in length, and between 1" and 3" in length.
- >> DCKL_WR, from the SDRAM clock driver to the GMCH, must be between 3.5" and 5.5" in length, and 2.5" longer than SDRAM_CLK[1:0].

IDE Specific Routing Requirements

- >> Place IDE conector within 8" of ICH.

Power Supply Specific Routing Requirements

- >> All unrelated signals and power planes must be kept away from the switching circuits.
- >> All traces associated with the input power/ground connectors, and the capacitors connected to these connectors, must be routed with minimum length and maximum width.
- >> See the Power Supply schematic sheet for complete restrictions.

Memory Bus Specific Routing Requirements

- >> Minimum trace width is 5 mils.
- >> Minimum space between traces is 10 mils, this includes adjacent signal layers.
- >> Minimum space between memory traces and other types of traces is 25 mils, this includes adjacent signal layers.
- >> Memory address, data, and control lines must be routed as separate groups and treated as different signal types.
- >> The MD, DQMA, CSA#, SRAS#, SCAS#, WE_A#, and MA signals (between GMCH and SODIMM) must be between 1" and 3" in length, matched to within 600 mils.

Memory Bus GROUPS -- SO-DIMM Names

- >> Address Signals: MAA[13:0]
- >> Data Signals: MD#[63:0]
- >> Control Signals:
 - SMBDATA, SMBCLK, CSA[1:0]#, WE_A#, SCAS#, SRAS#

PCI Bus Specific Routing Requirements

- >> PCI bus max length must be less than 6".

PCI Bus GROUPS

- >> Address/Data Signals: AD[31:0]
- >> Control Signals:
 - C/BE[3:0]#, REQ[4:1]#, GNT[4:1]#, INT[A:D]#, PCIRST#, FRAME#, TRDY#, IRDY#, STOP#, DEVSEL#, SERR#, PERR#, PAR, LOCK#

HUB Bus GROUPS

- >> Address/Data Signals: HL[10:0]
- >> Control Signals: HLSTB,HLSTB# (differential strobe pair).
- >> HL[10:0] should be routed with a trace width of 5 mils and a trace spacing of 20 mils. These signals can be routed with a trace width of 5 mils and a trace spacing of 15 mils for navigation around components or mounting holes. The maximum trace length for the hub interface data signals is 7". These signals should each be matched within .1" of the HLSTB and HLSTB# signals.

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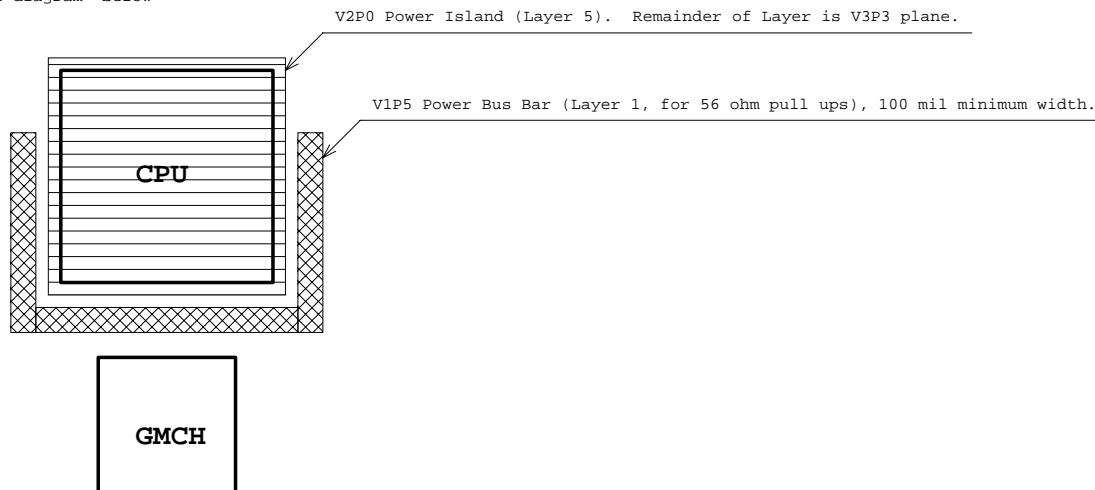
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General Placement Requirements

>> Place major components and connectors as shown in the Mechanical drawings.

CPU/GMCH Specific Routing Requirements.

>> Rotate the CPU and GMCH chips so as to minimize the length of the connections between the two, and place as shown in the diagram below:



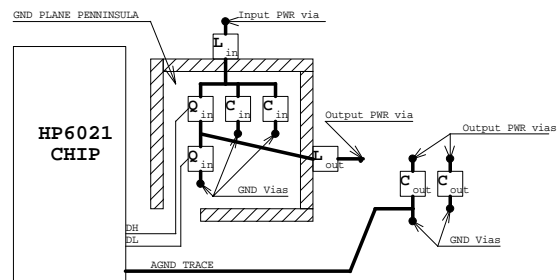
>> The V2P0 power supply must not be layed over the V2P0 power island. The power supply feed to the power island must be the maximum practical width.

>> The V1P5 power supply must not be layed over the V1P5 power island. The power supply feed to the power island must be the maximum practical width.

>> The V2P0 power island depiction above, is approximate, and must be large enough to fully encompass the entire CPU as well as any component that connects to the V2P0 supply.

Power Supply specific Routing Requirements.

>> The diagram below depicts the placement requirements for the SC1164 switching regulator circuits. A GND plane penninsula is used to contain the high current and noisy switching components. All of the bold traces and vias shown have high current and low impedance requirements. These trace widths should be 100 mils minimum. The channel which connects the GND penninsula to the main GND plane must be 500 mils in width.



>> No other signals may be routed underneath the GND plane penninsula.

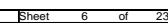
>> No other power planes may exist underneath the GND plane penninsula.

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The schematic diagram illustrates a 16-channel multi-electrode array (MEA) system. It is organized into two horizontal rows, each containing 16 identical channel units. Each channel unit consists of a V1P5 input terminal at the top, followed by a resistor labeled with a component number (C186 through C224 in the top row, and C238 through C283 in the bottom row). Below each resistor is a 0.1uF 16V capacitor connected to a common ground symbol. The components are arranged in a grid-like fashion, with the input terminals aligned horizontally and the capacitors aligned vertically.

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V1P5

R160
75 1%

R161
150 1%

C223
0.1uF
16V

C203
0.01uF
16V

C207
1uF
16V

GMCHGTLREF

17 GMCHHCLK

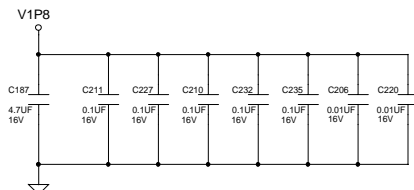
11,13

R158

C204
N/A
16V

Do not Stuff

Place site w/in 0.5" of clock ball (V6)



5.7 HA#[31:3] <<

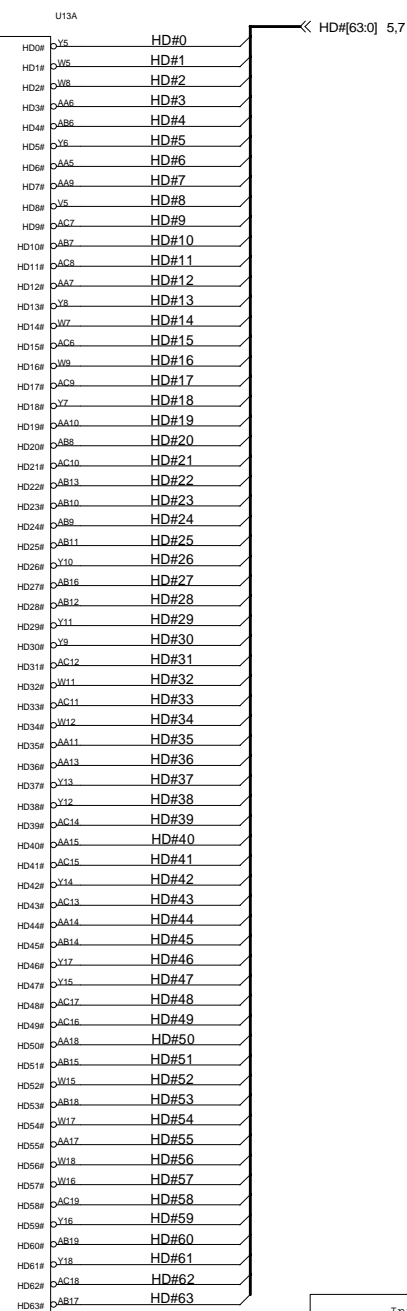
HA#3	U3C	HA3#
HA#4	U1C	HA4#
HA#5	V4C	HA5#
HA#6	V1C	HA6#
HA#7	T4C	HA7#
HA#8	U2C	HA8#
HA#9	U3C	HA9#
HA#10	W1C	HA10#
HA#11	U4C	HA11#
HA#12	W3C	HA12#
HA#13	W4C	HA13#
HA#14	T5C	HA14#
HA#15	W2C	HA15#
HA#16	V2C	HA16#
HA#17	AC2C	HA17#
HA#18	AA2C	HA18#
HA#19	Y3C	HA19#
HA#20	AB3C	HA20#
HA#21	AA1C	HA21#
HA#22	AB2C	HA22#
HA#23	AC3C	HA23#
HA#24	AA3C	HA24#
HA#25	Y2C	HA25#
HA#26	AB5C	HA26#
HA#27	ACA4C	HA27#
HA#28	Y1C	HA28#
HA#29	ACS4C	HA29#
HA#30	YA4C	HA30#
HA#31	AB1C	HA31#

5.7 HREQ#[4:0] <<

HREQ#0	B4C	HREQ0#
HREQ#1	T2C	HREQ1#
HREQ#2	P4C	HREQ2#
HREQ#3	B2C	HREQ3#
HREQ#4	B5C	HREQ4#

5.7 RS#[2:0] <<

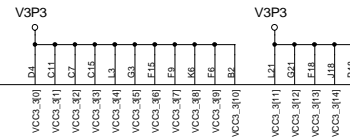
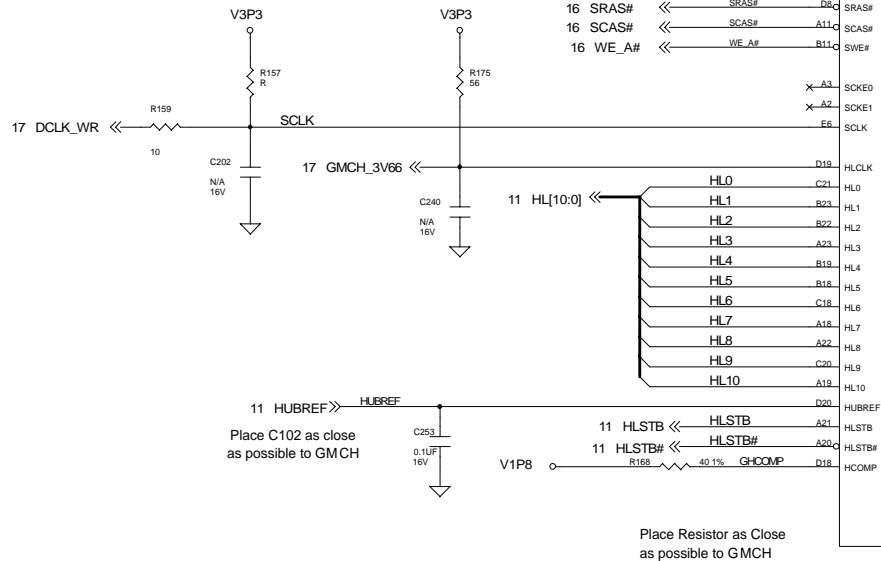
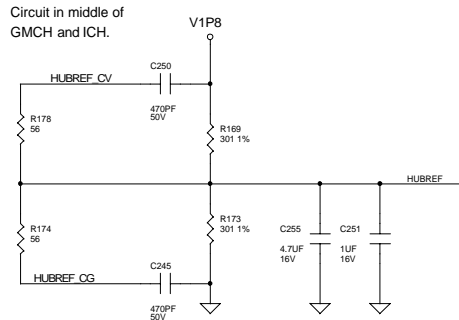
RS#0	N5C	RS0#
RS#1	P2C	RS1#
RS#2	N2C	RS2#



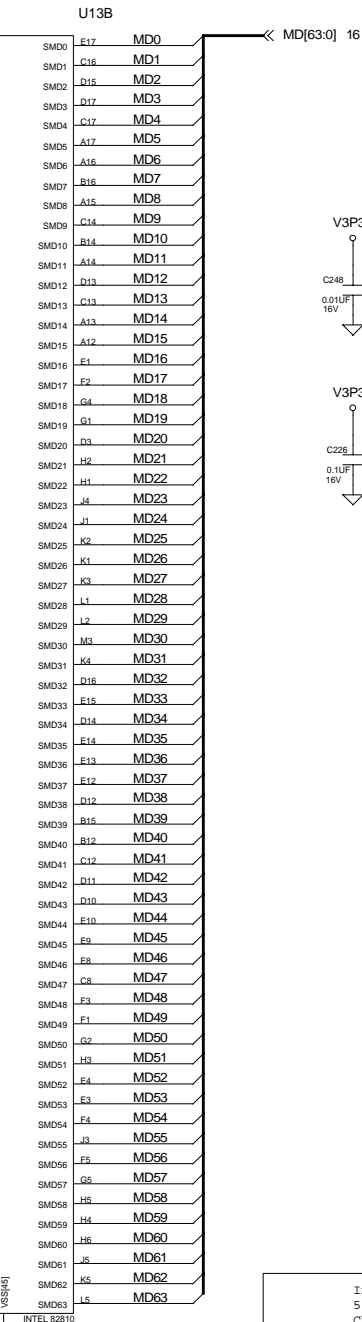
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82810 PART 2: SYSTEM MEMORY AND HUB INTERFACE

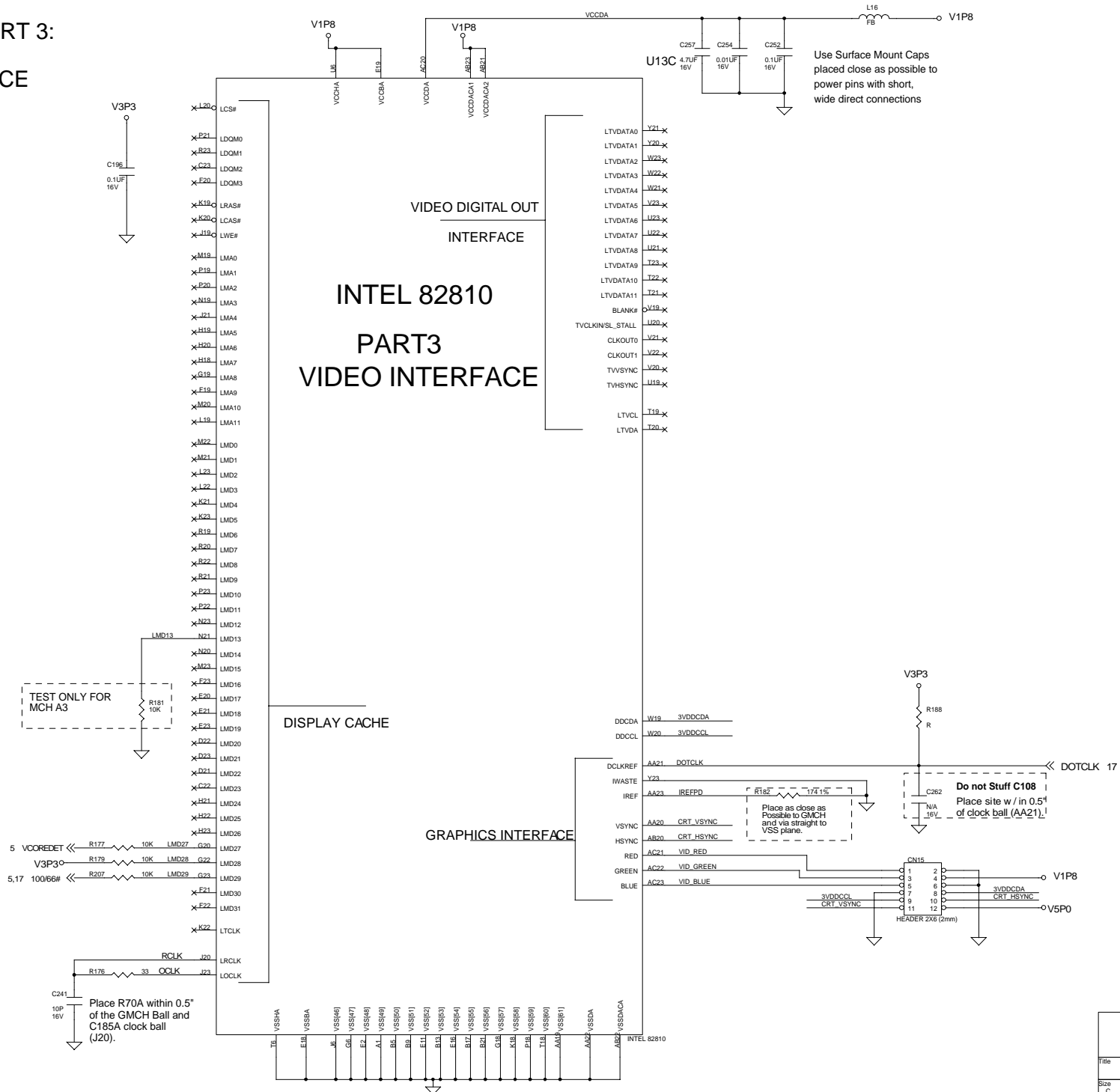
Place HUBREF Generation



INTEL 82810 PART 2 SYSTEM MEMORY AND HUB INTERFACE

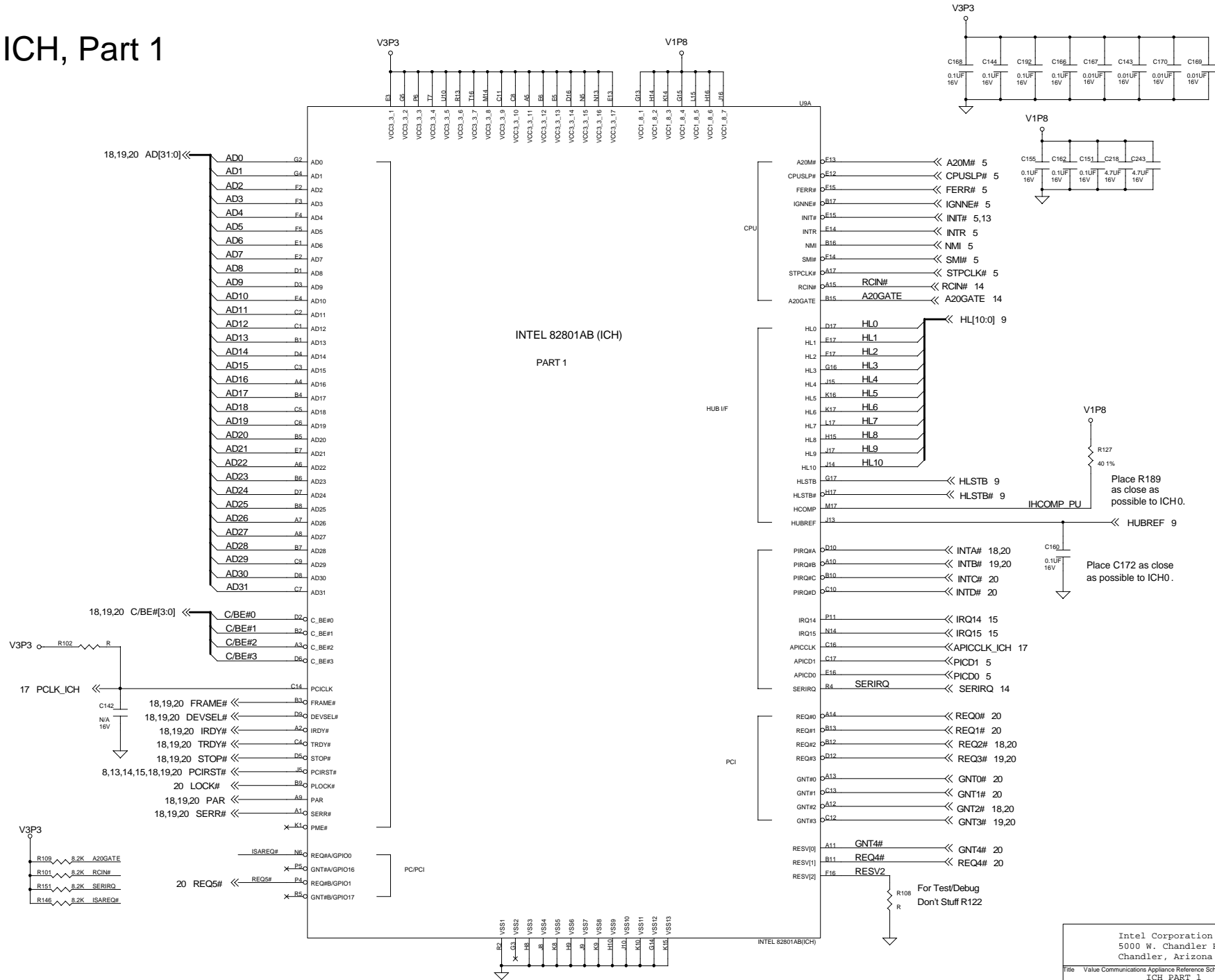


82810 PART 3: DISPLAY INTERFACE



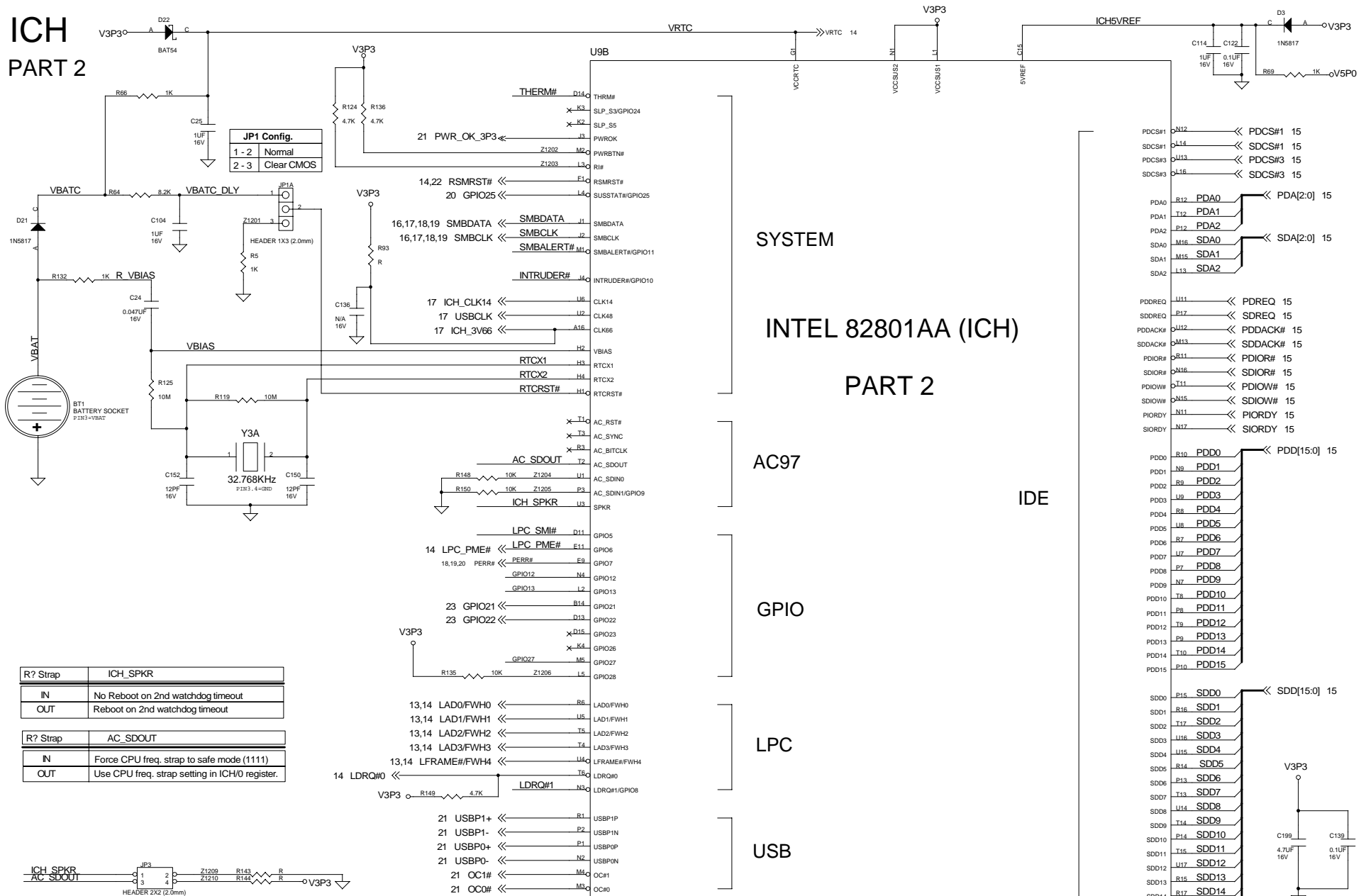
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ICH, Part 1



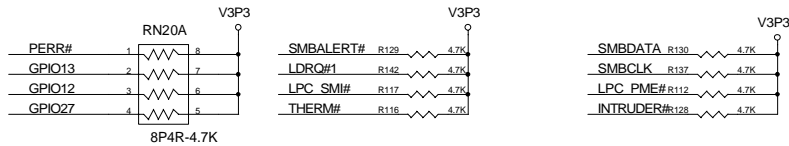
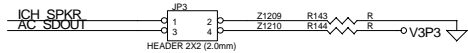
ICH

PART 2



R? Strap	ICH_SPKR
IN	No Reboot on 2nd watchdog timeout
OUT	Reboot on 2nd watchdog timeout

R? Strap	AC_SDOUT
IN	Force CPU freq. strap to safe mode (1111)
OUT	Use CPU freq. strap setting in ICH/I/O register.



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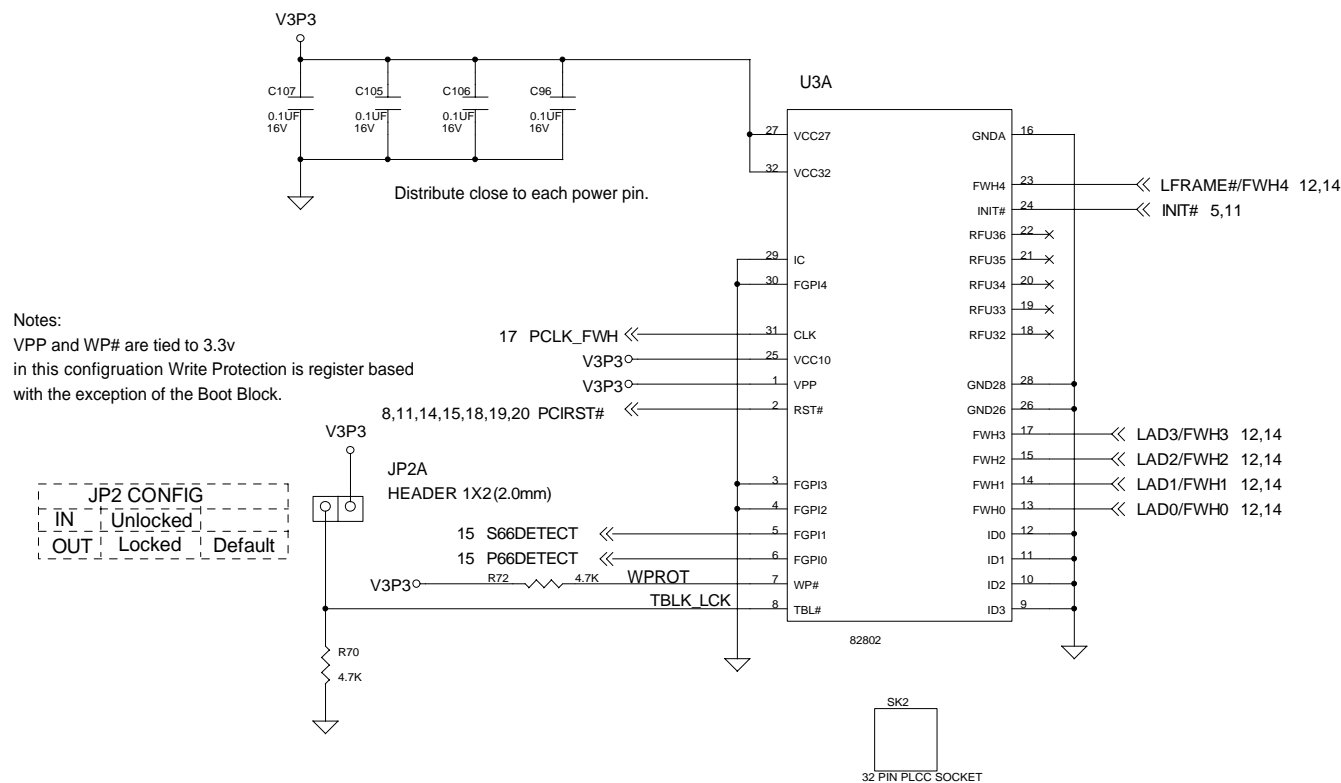
ICH Part 2

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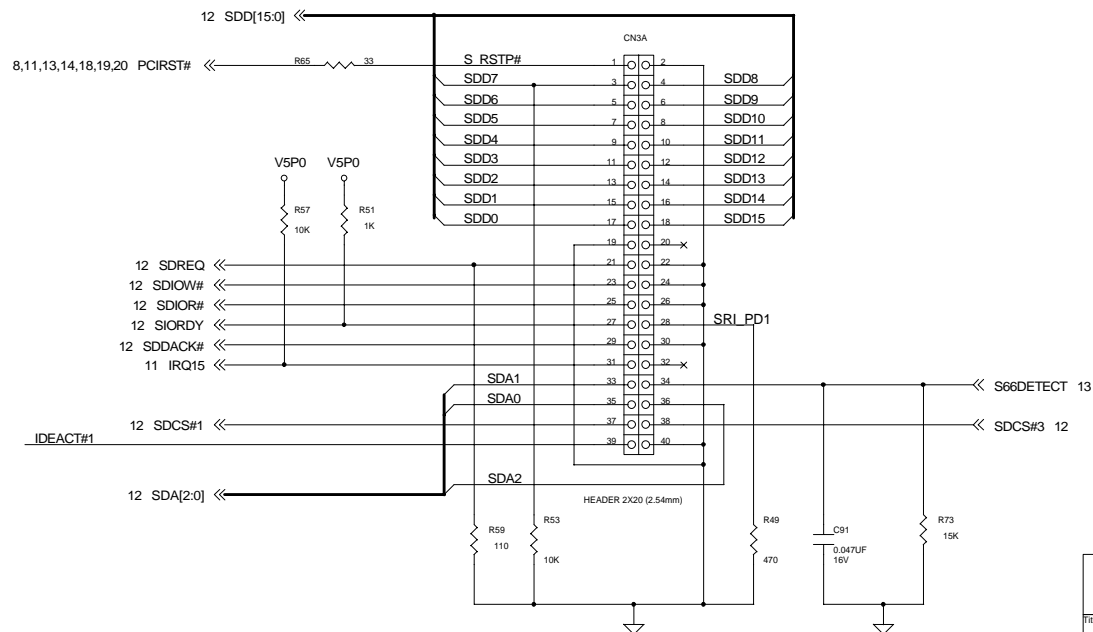
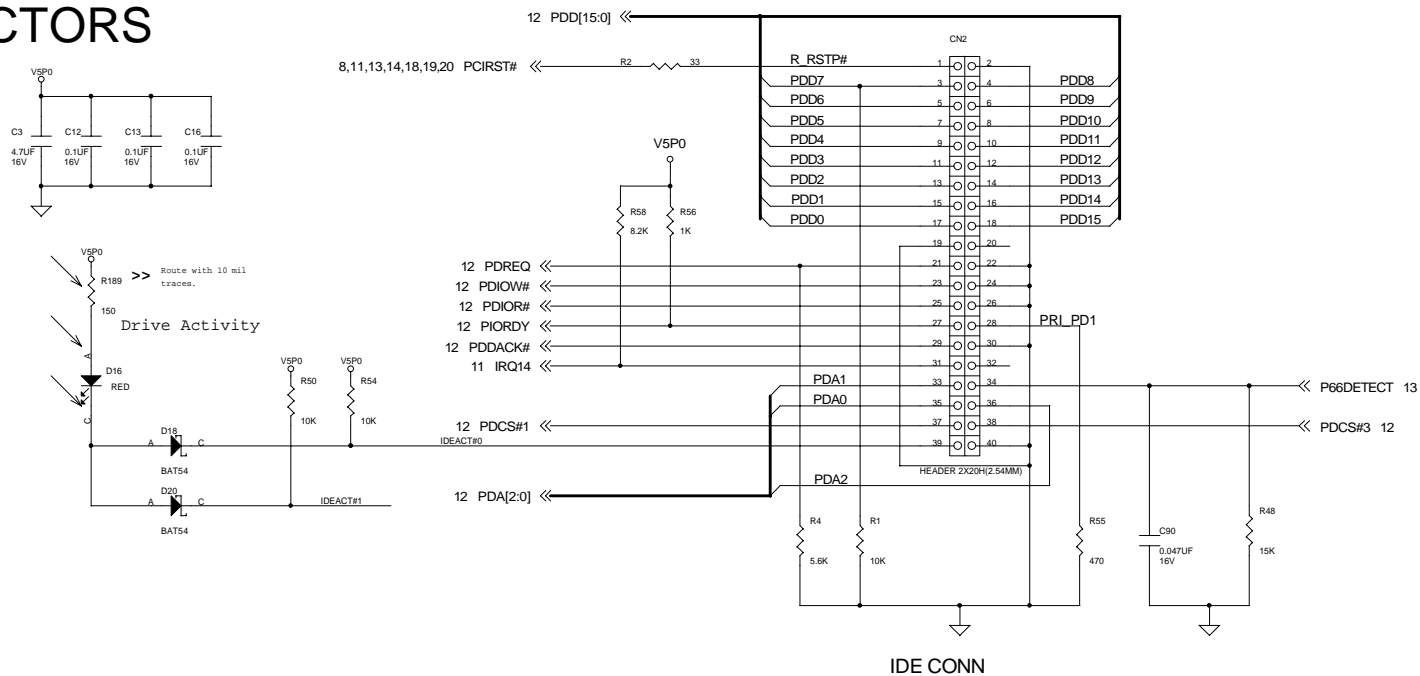
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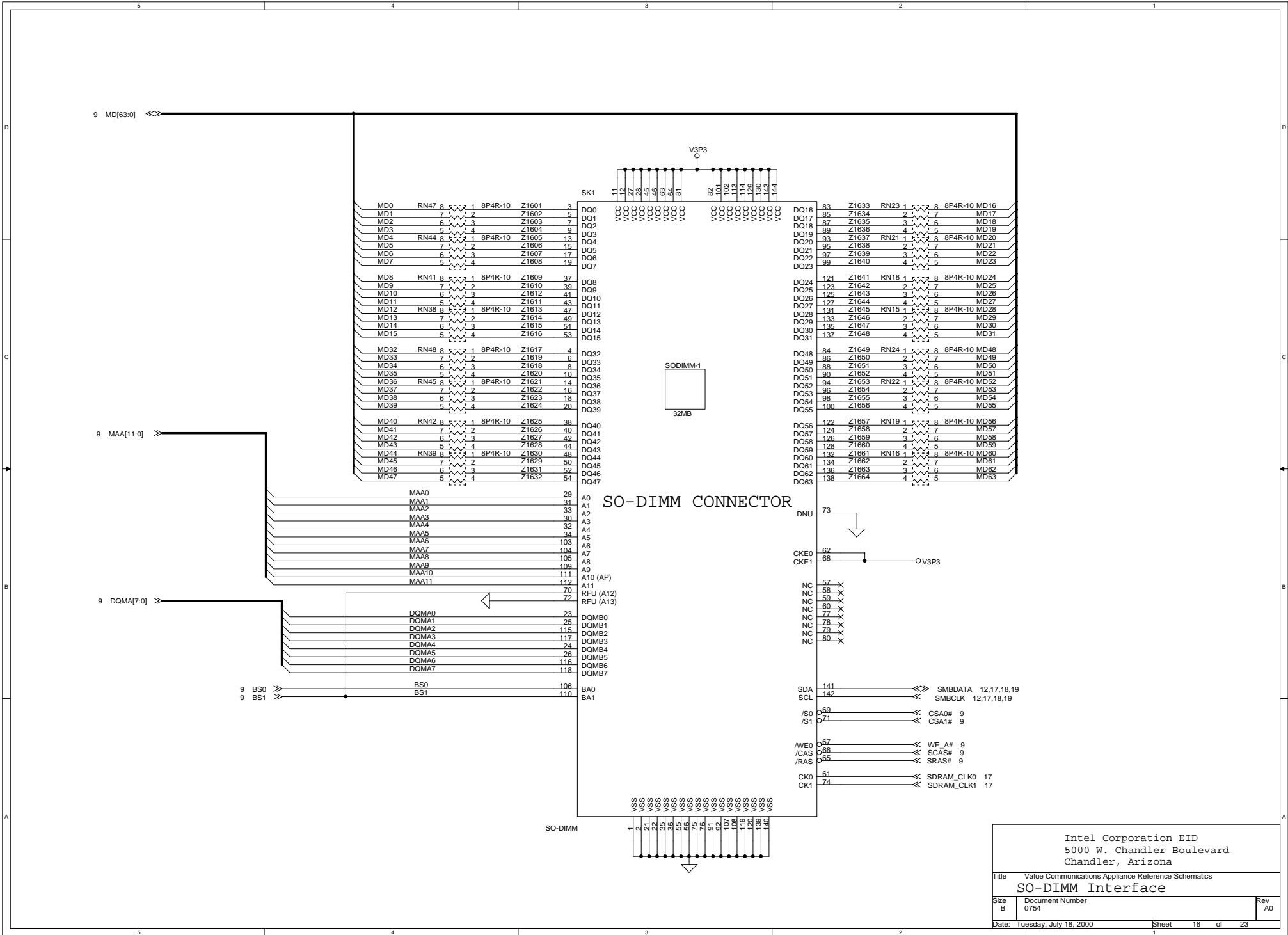
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FirmWare Hub (FWH)

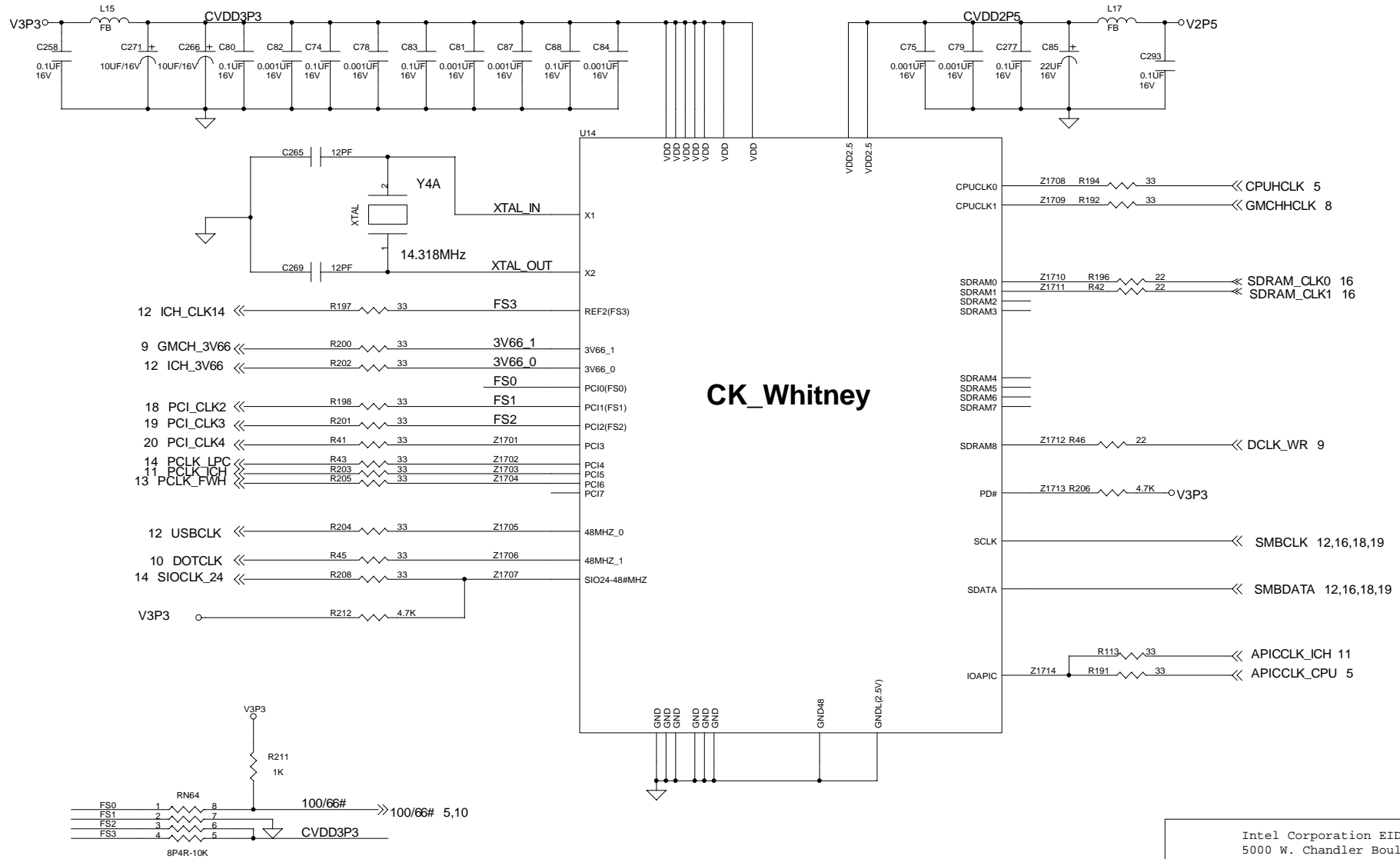


ULTRA ATA33/66 IDE CONNECTORS





Clock Synthesizer



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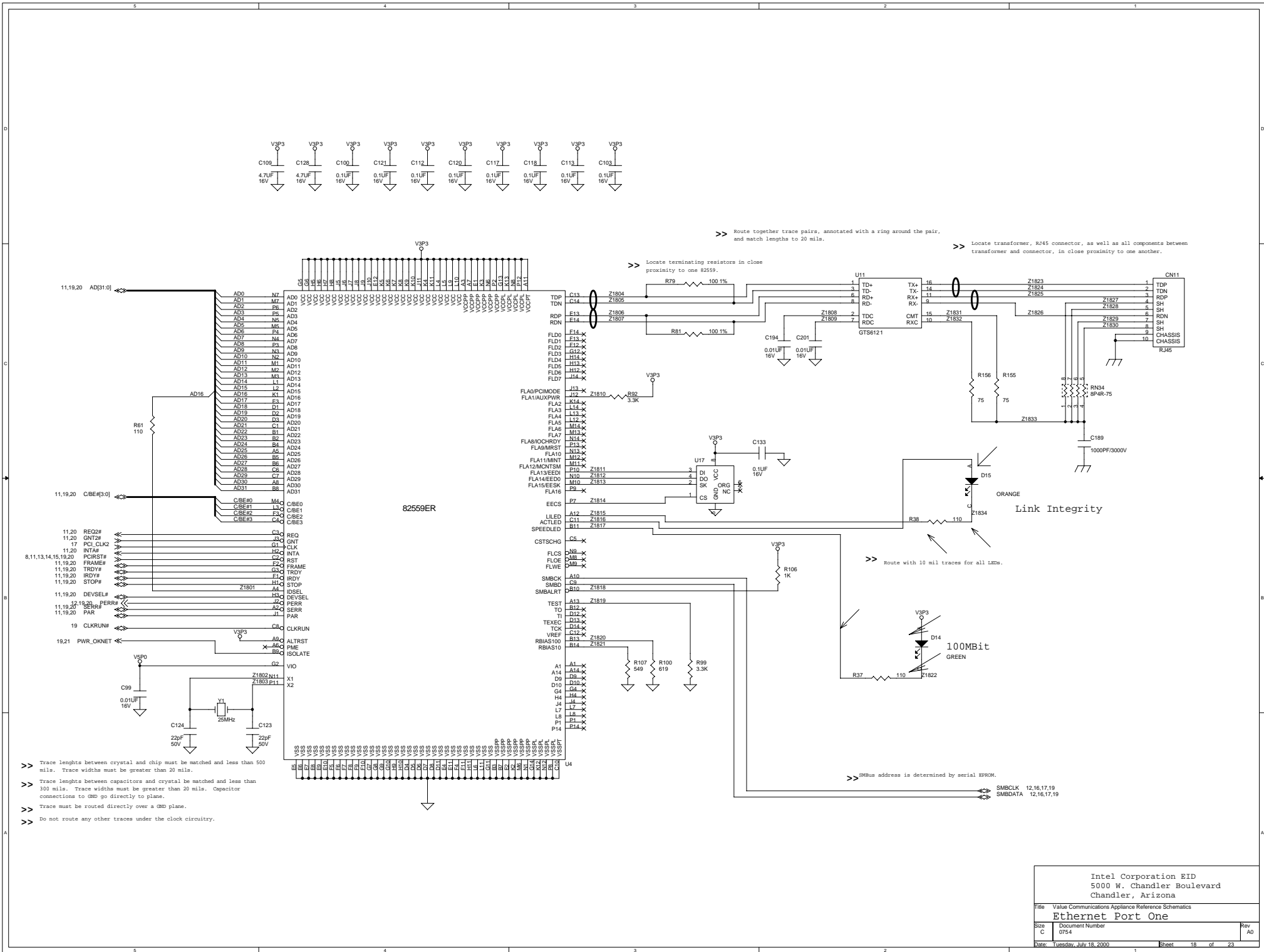
Clock Generator

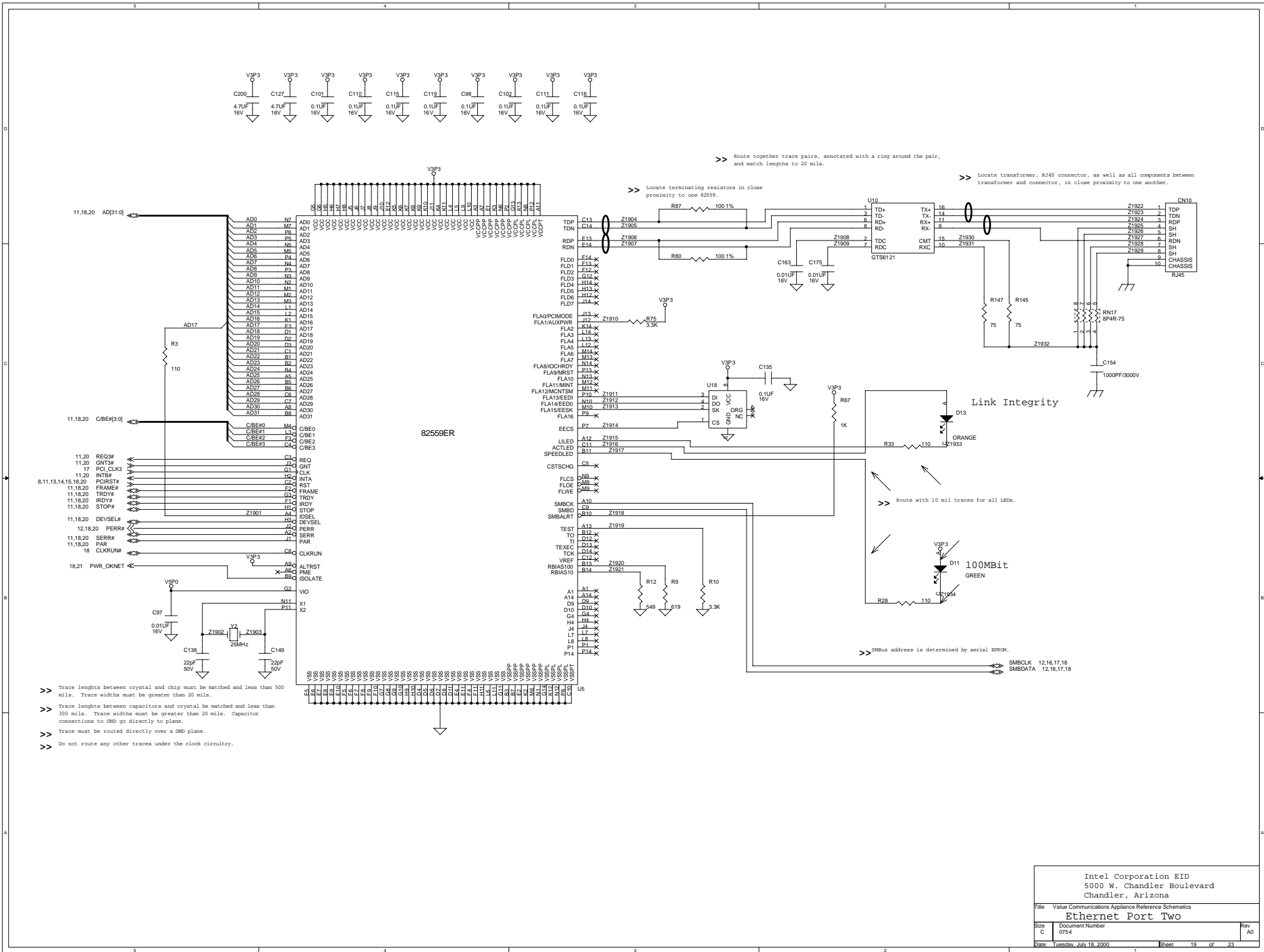
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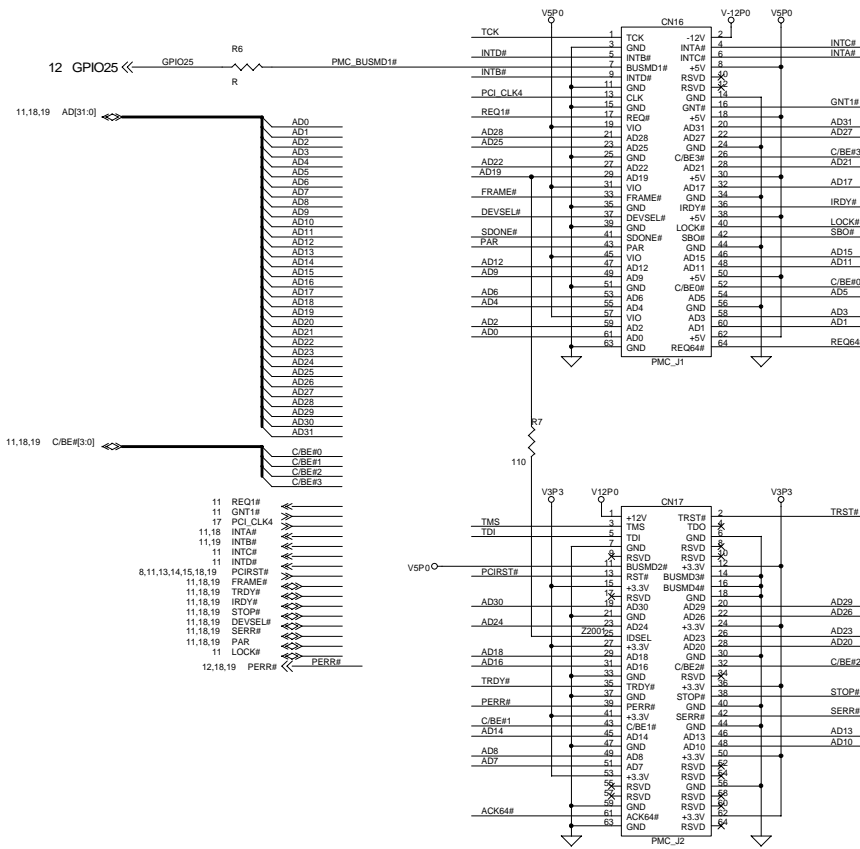
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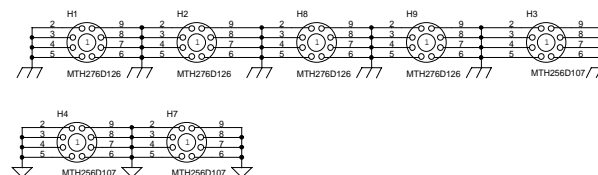
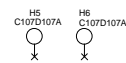
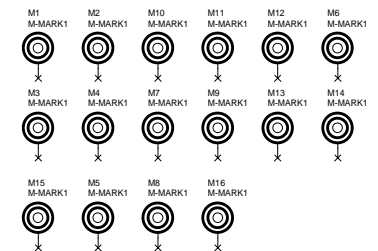
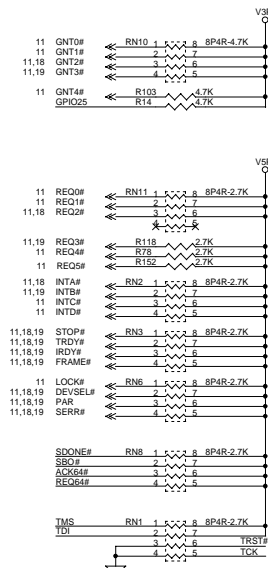
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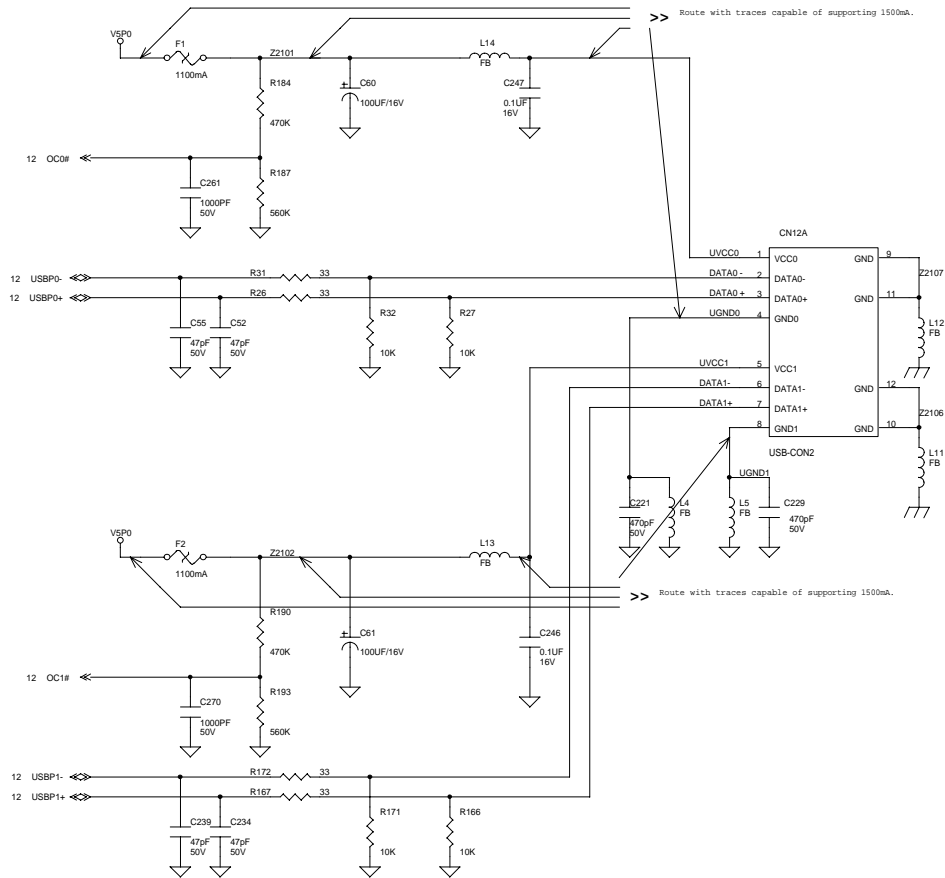


PCI Pullups

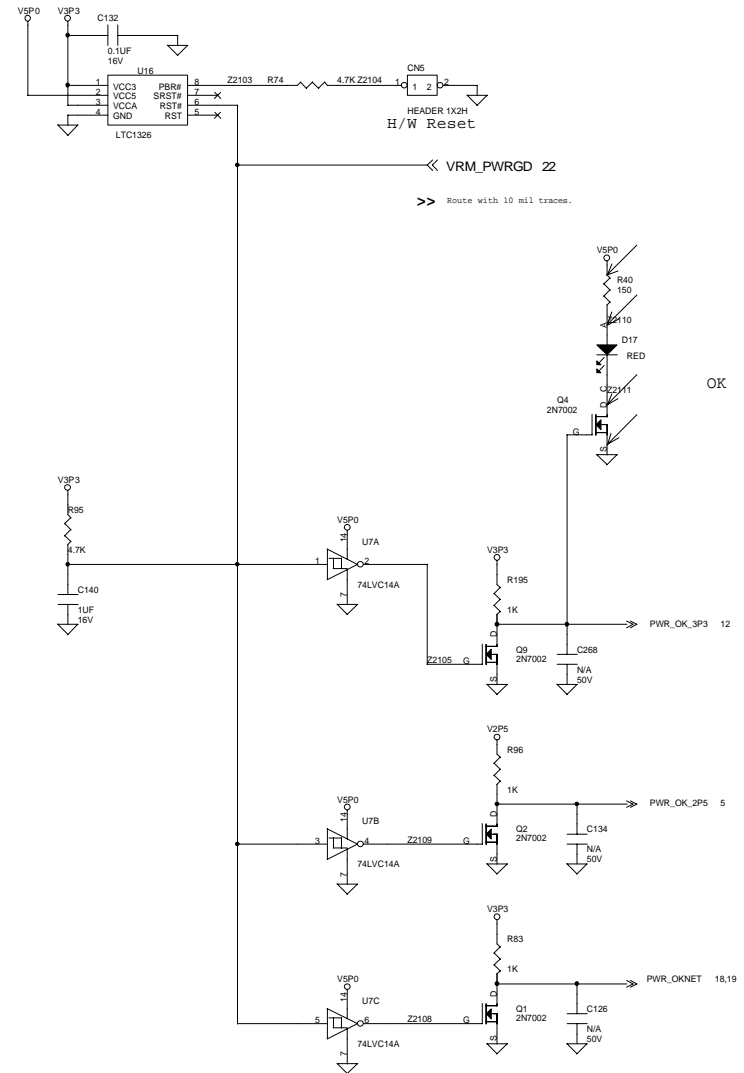


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USB CIRCUITRY



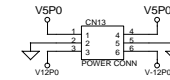
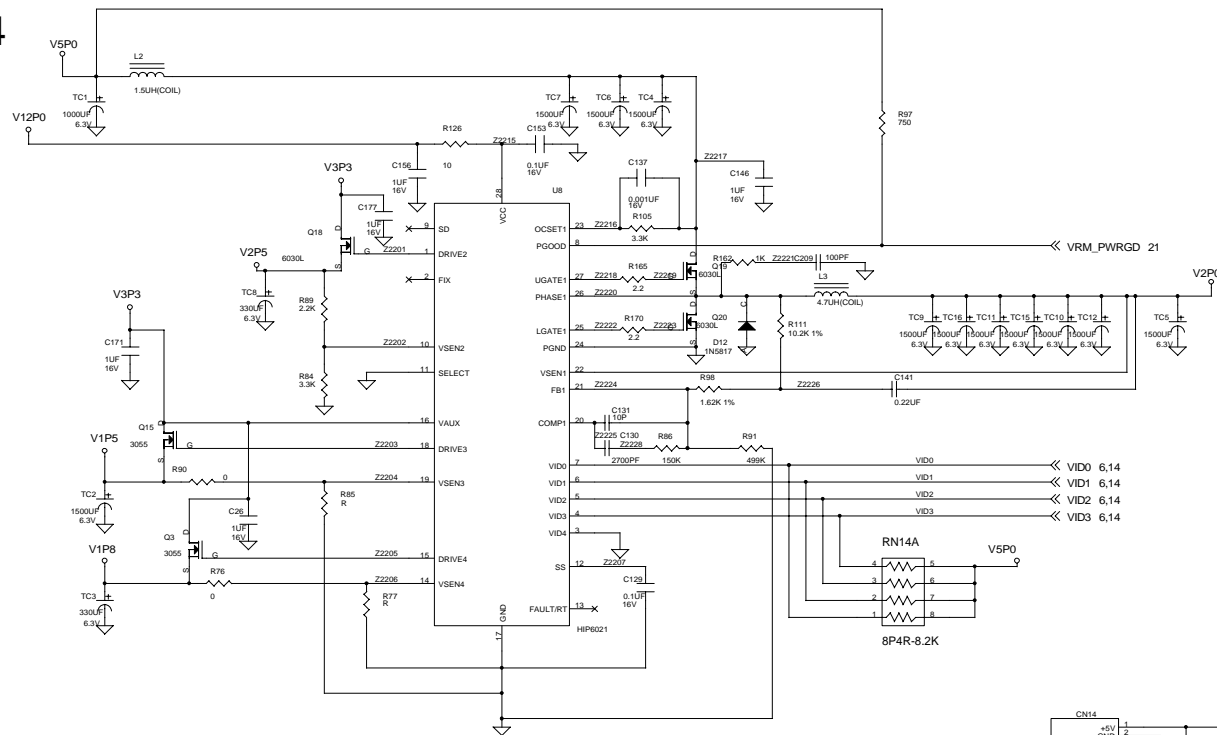
RESET CIRCUITRY



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VRM 8.4



Resume Reset Circuitry

Schmitt Trigger Logic using a 22msec delay

